Oxford nanoSystems

nanoFLUX: Potential Applications for Microporous Coatings

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A bit about me

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- OnS for 2 years

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- RoyalCom1851 Industry Fellow w/UCL

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- 2016 start development contracting

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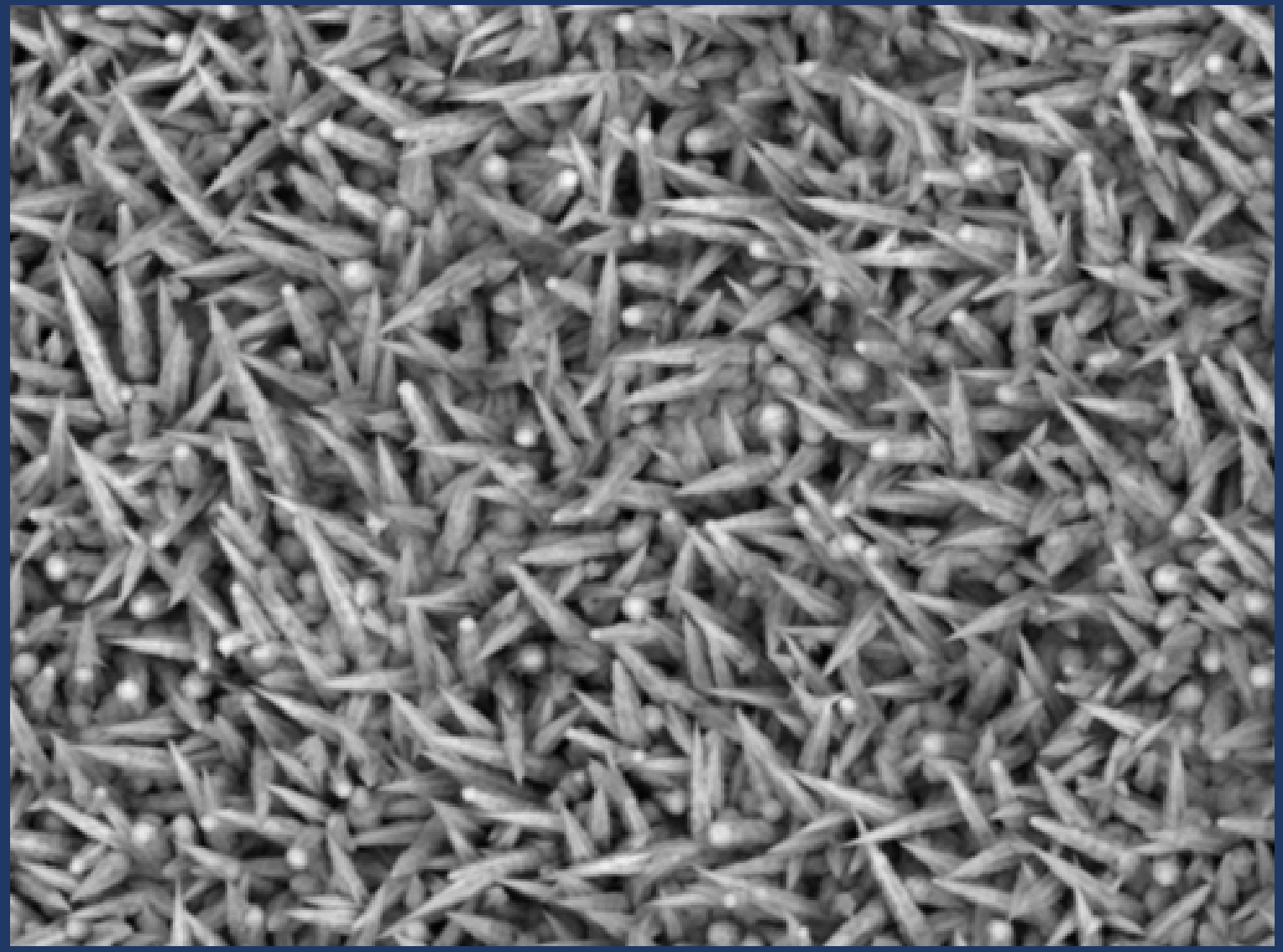

nanoFLUX: Application Process

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- DI rinse
- nanoPROTECT applied

Pool Boiling

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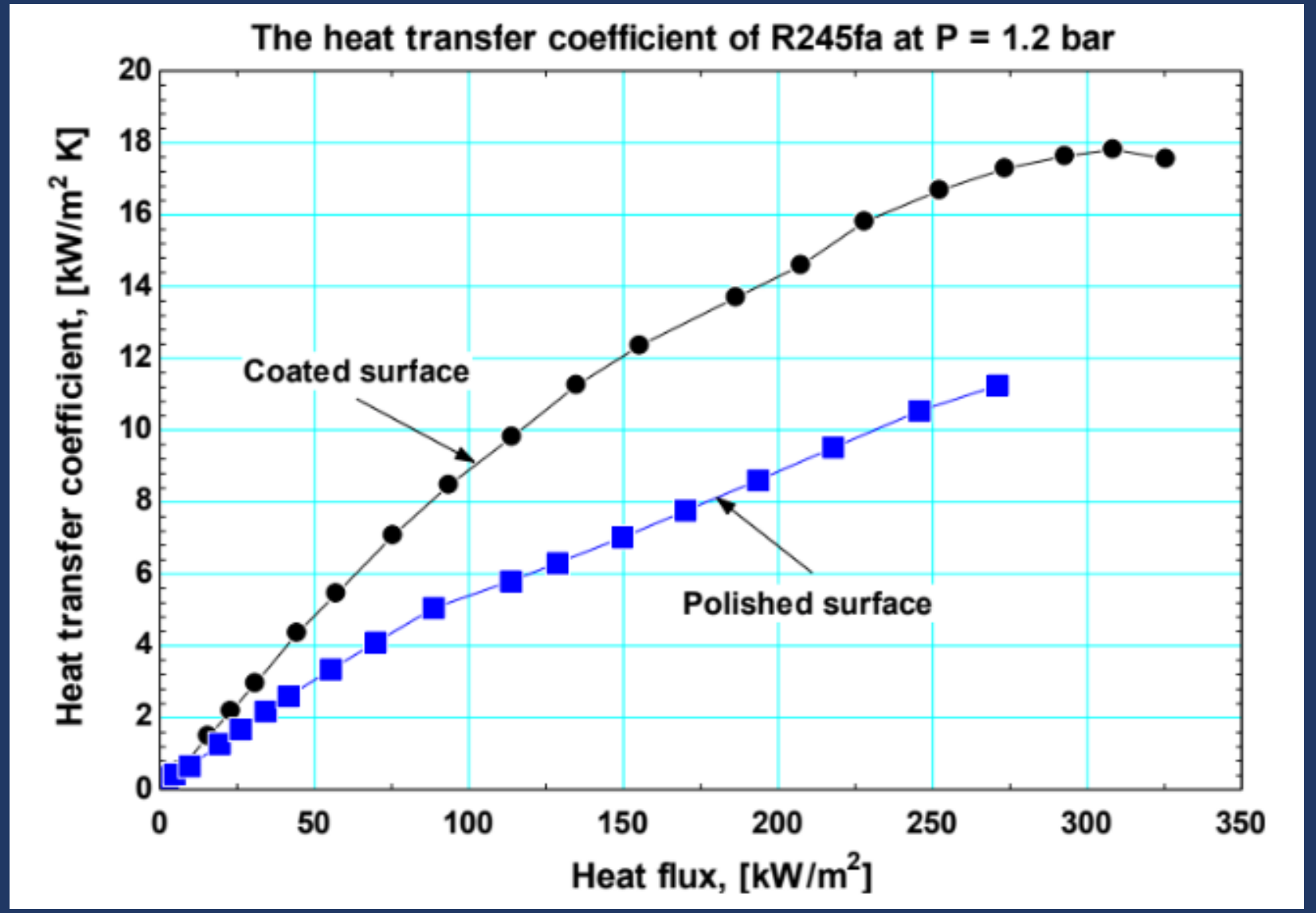

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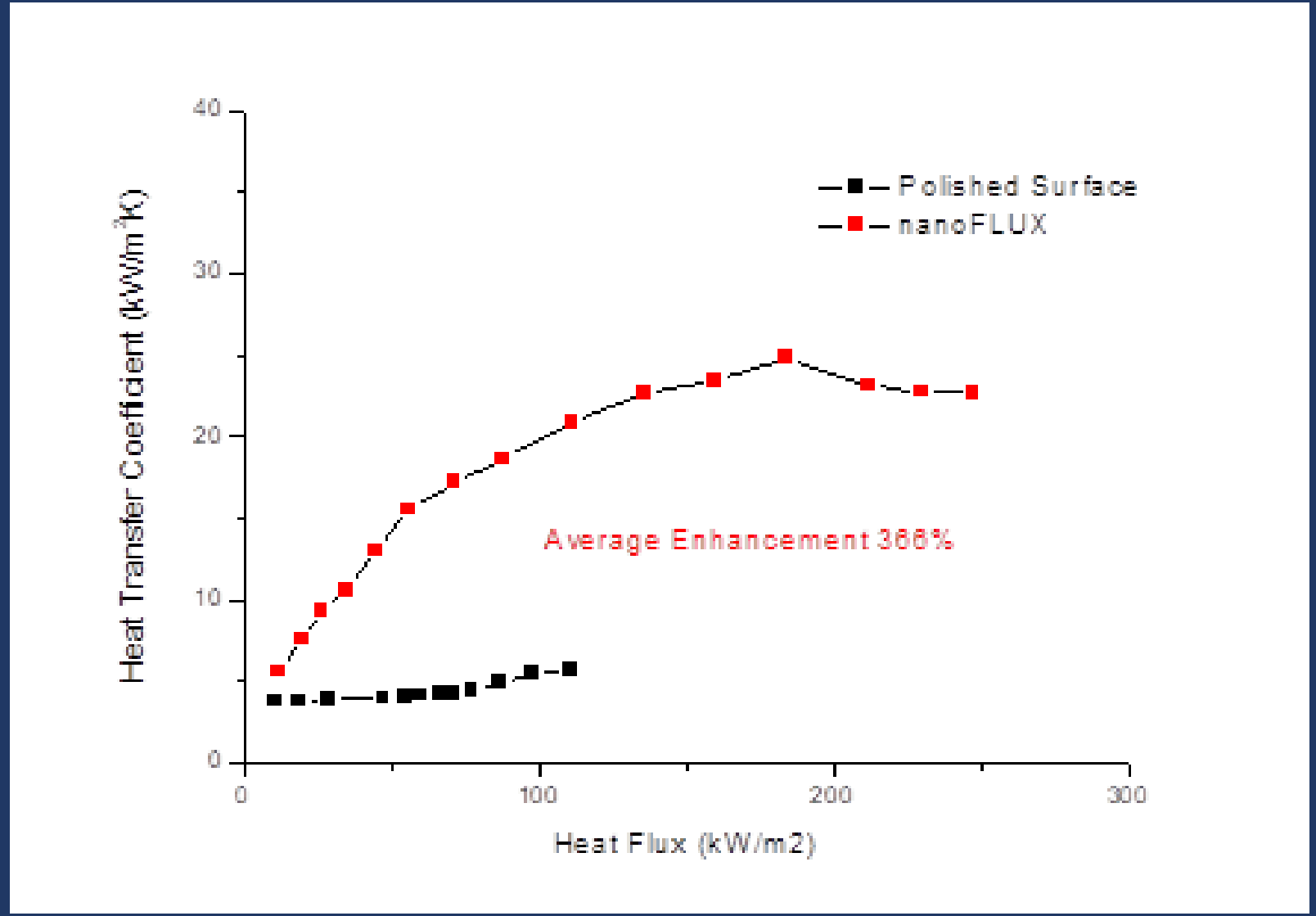

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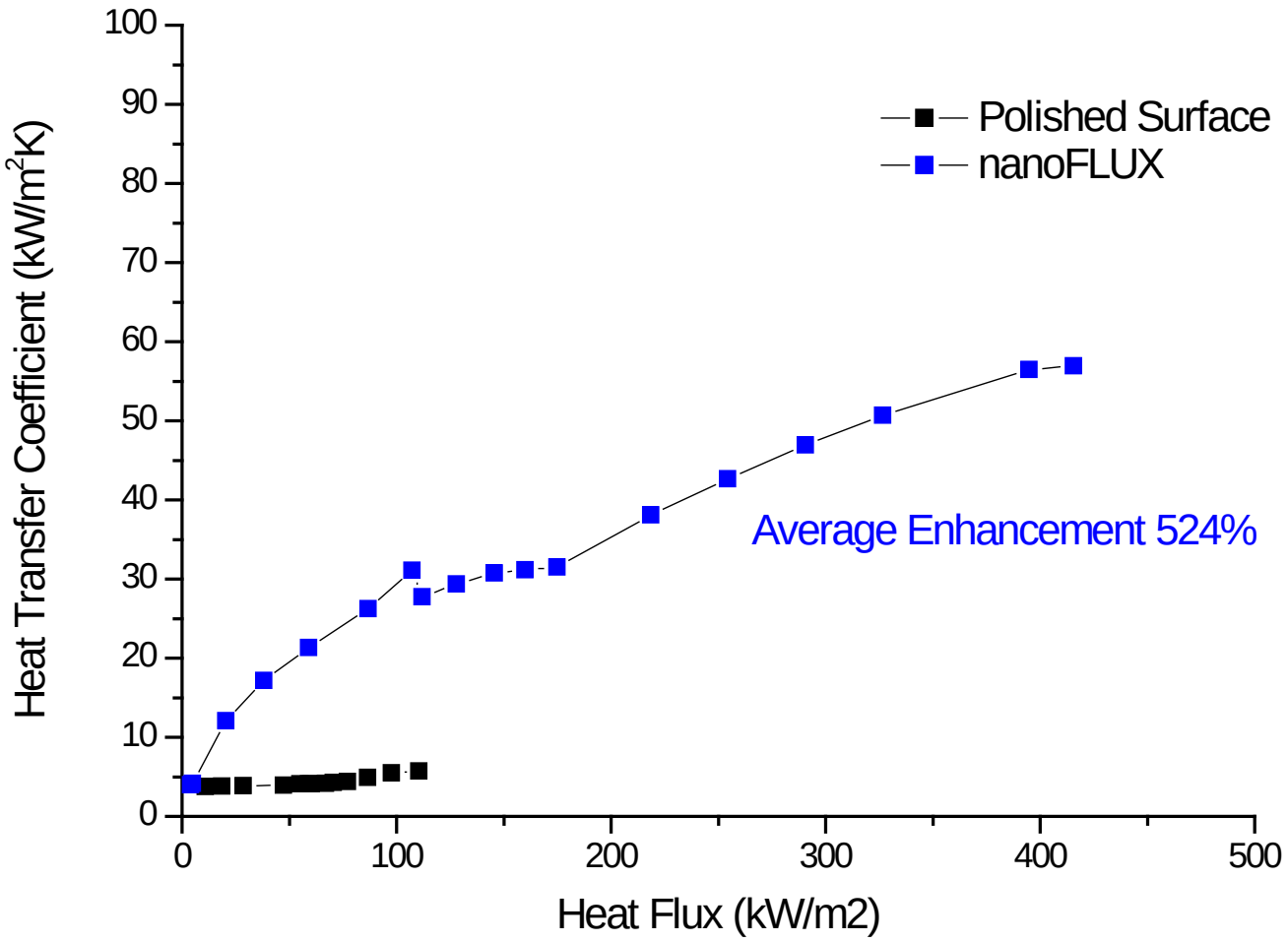

Flow Boiling

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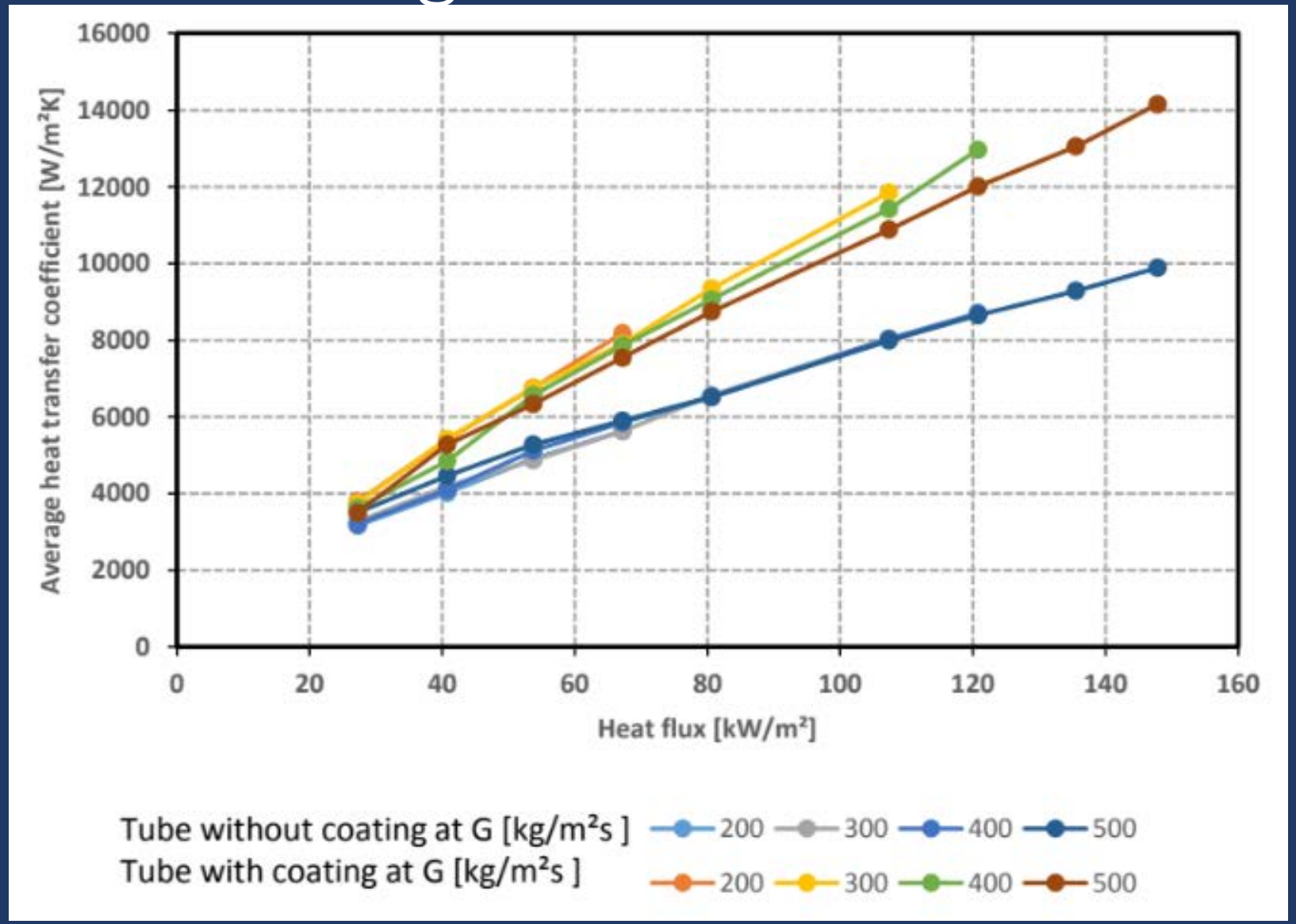

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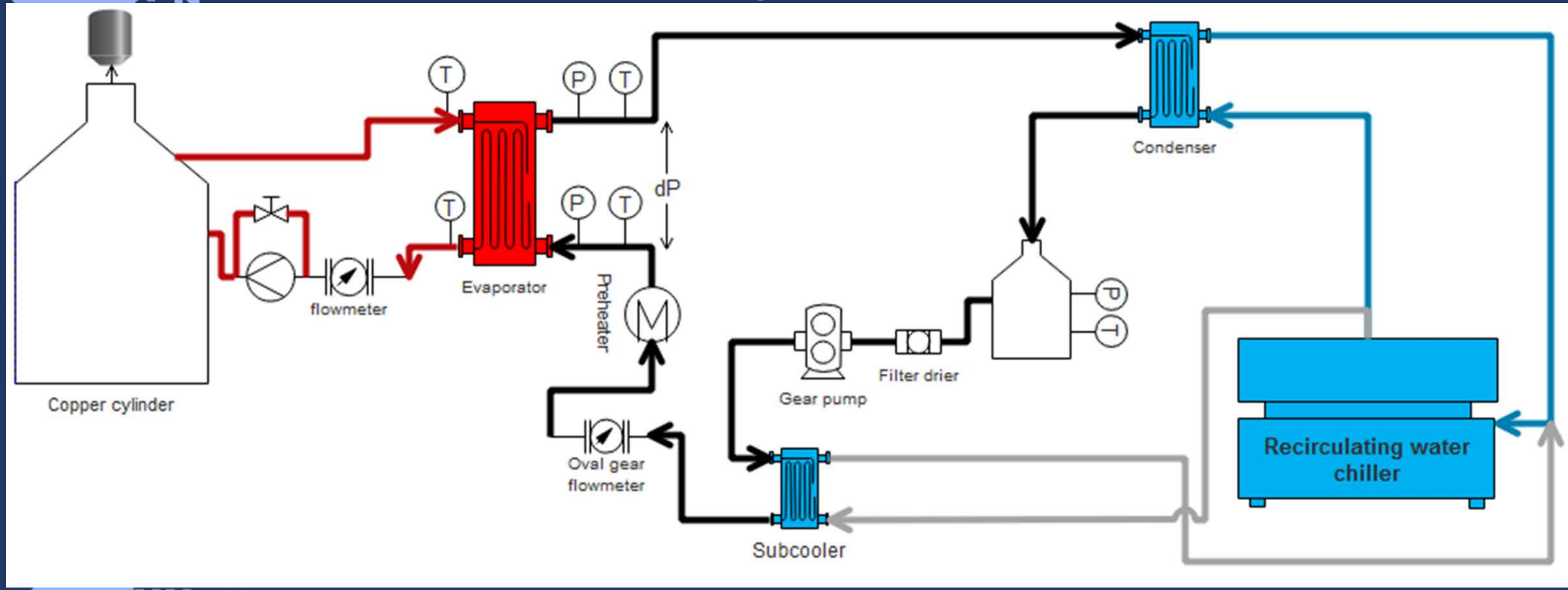

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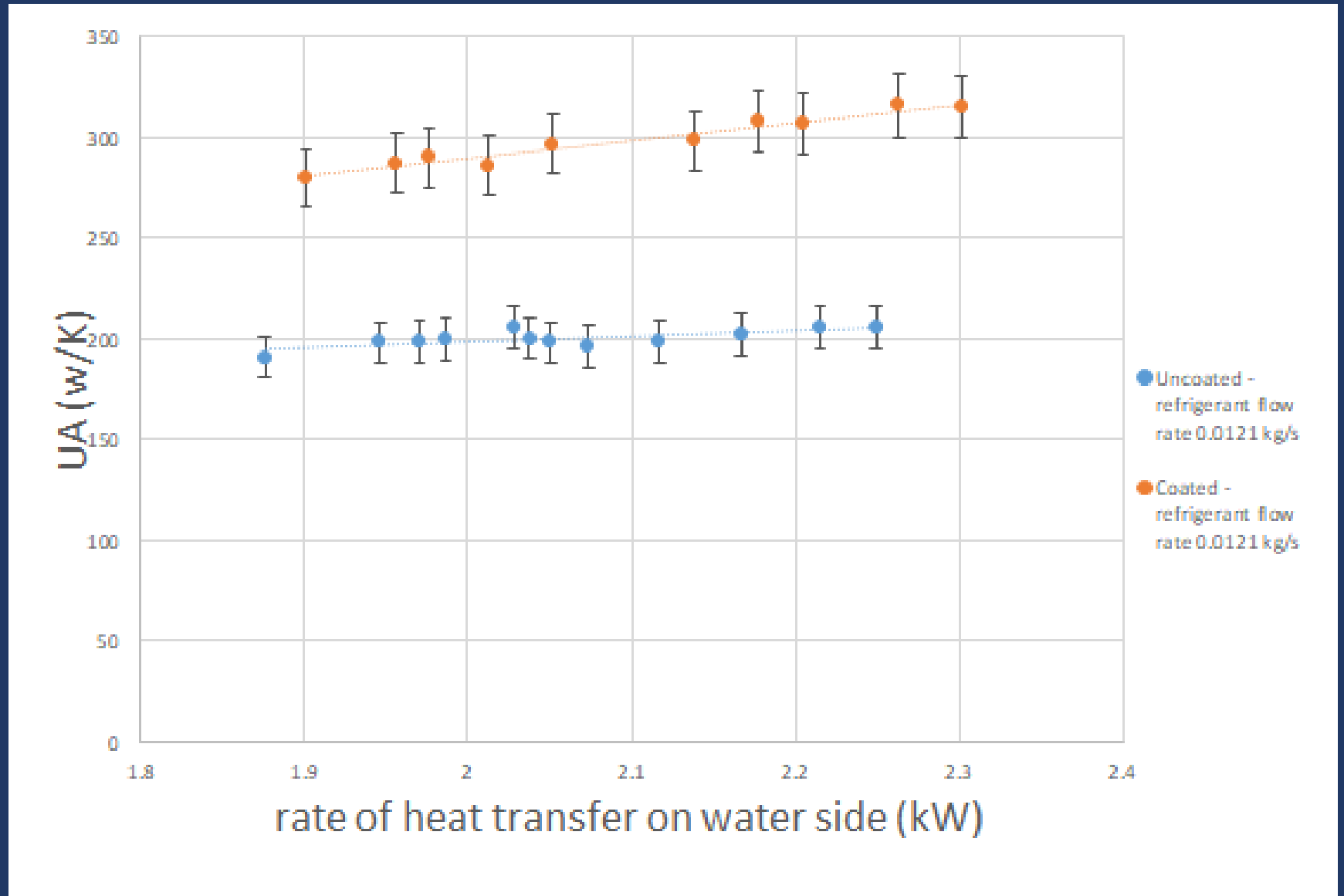

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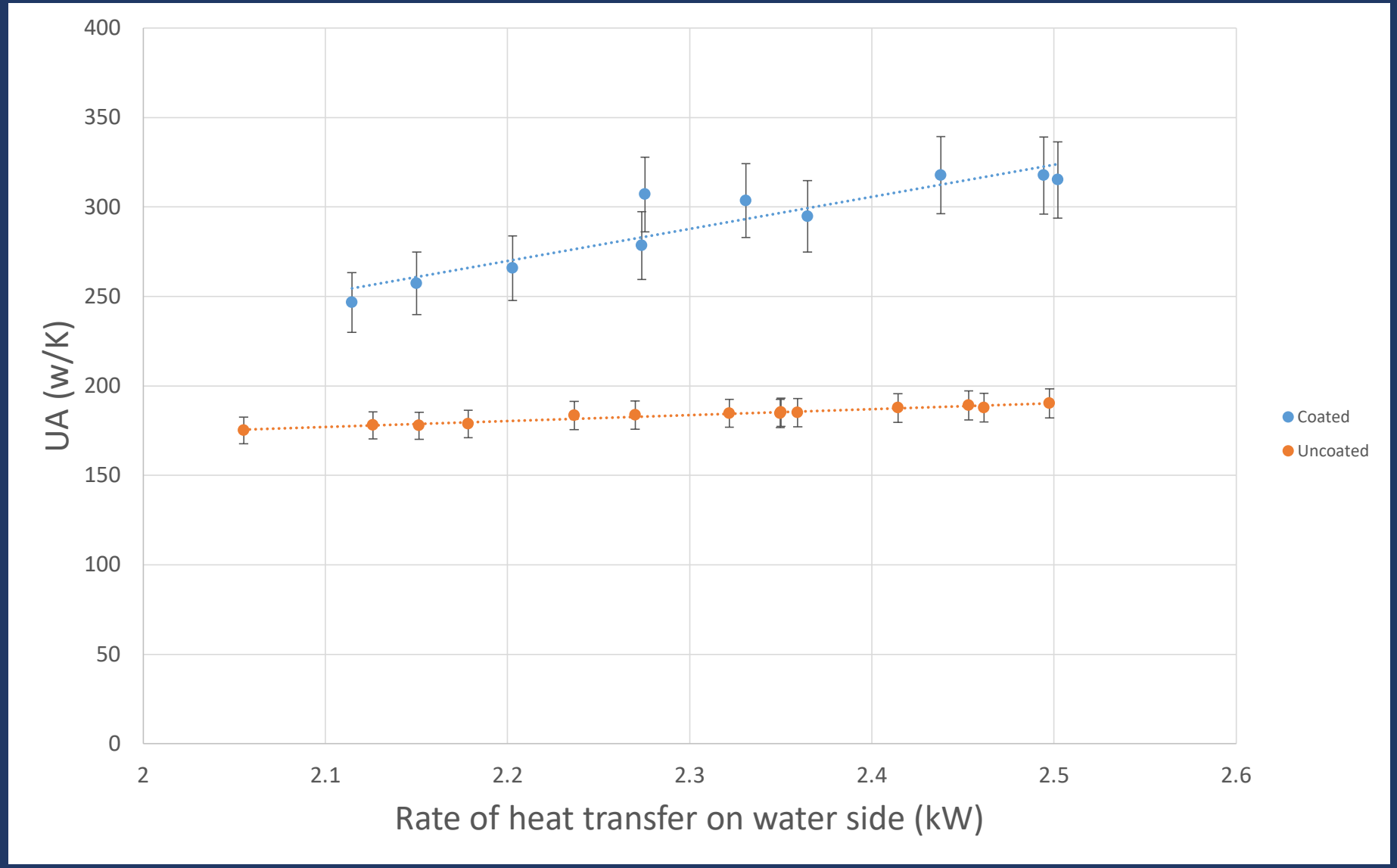
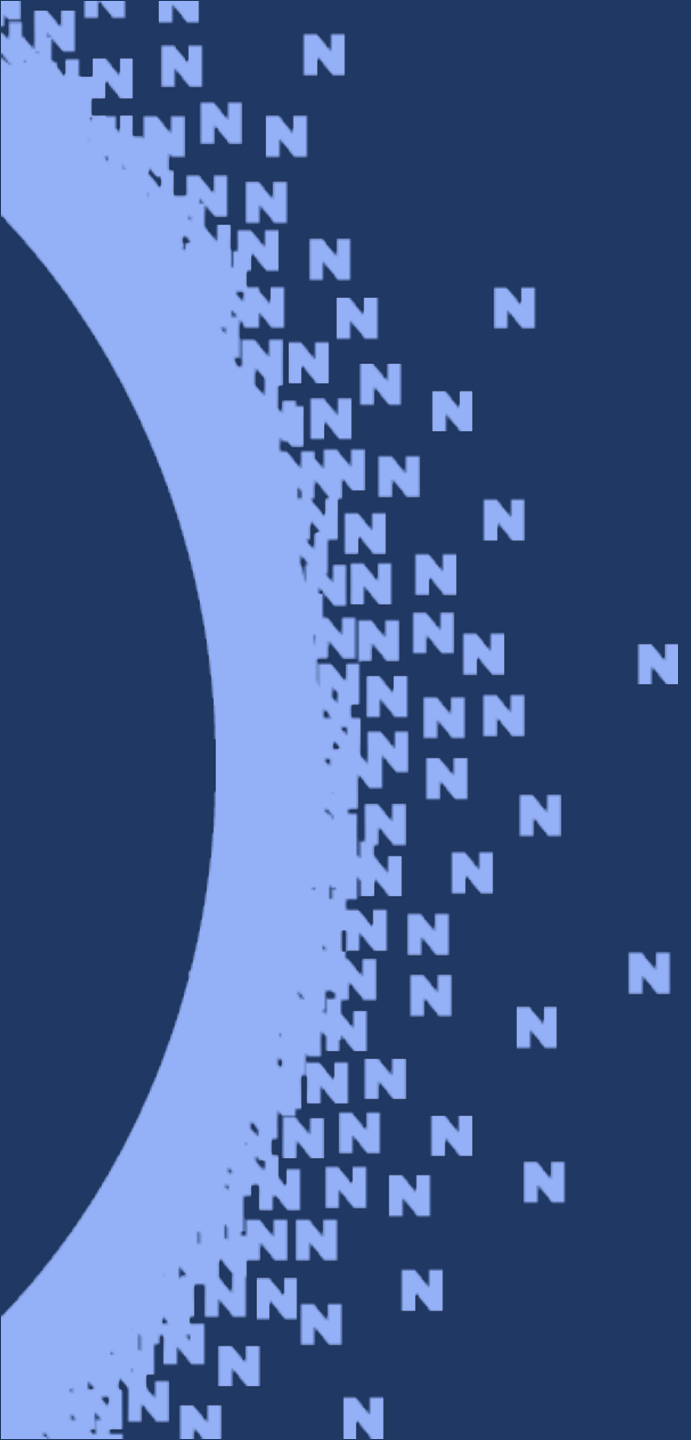


Size Reduction



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- Less work at compressor

Power Generation

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- Increased CHP
- More viable ORC sources

Thermal Stability

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- Other applications

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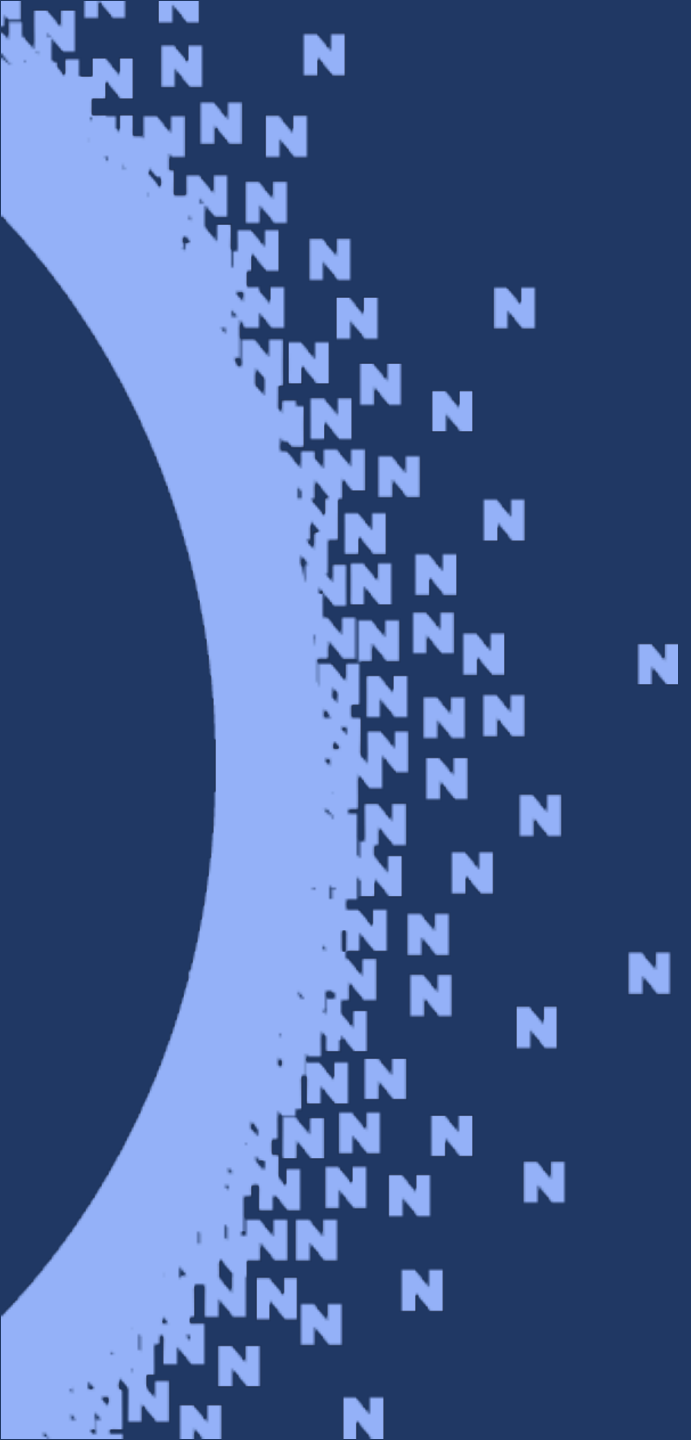
- Lack of knowledge at scale



Thank you for listening

Any Questions?